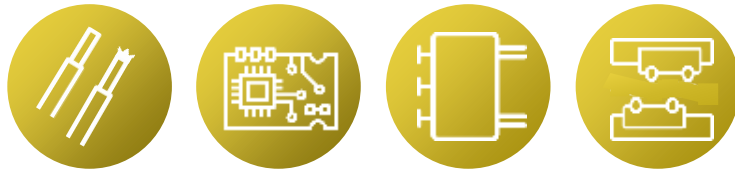


SEK SEIKEN

TOTAL TEST SOLUTION

Testing support and High-fine pitch test technology



Sales division
Head office
Antonio Fermin

February 26 2026



Company profile

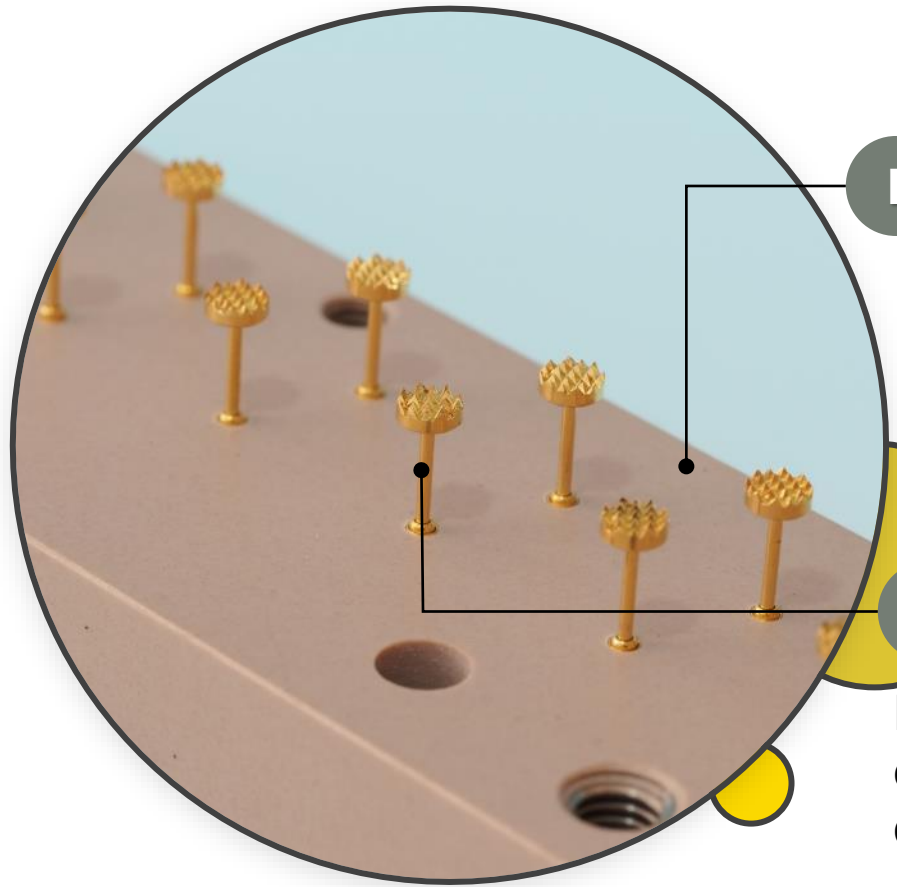


Company name :	Seiken Co., Ltd.
Foundation :	1984
CEO :	Takeshi Shiratori
Capital :	48 million yen
Annual revenues:	700 million yen
Number of employees :	Approx 70 employees
Branch offices :	Tokyo, Central area, Osaka, Fukuoka, Taiwan Nagano (Factory)
Automotive clients:	Murata Manufacturing, TDK, and others.
E-mobility experience:	Toshiba, Mitsubishi, Rohm, Lapis, etc.
Schaeffler experience:	We currently do not have any direct business
VDA 6.3 standard:	We are not currently audited to VDA 6.3

Nagano Factory



Main Product



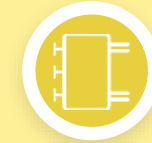
Resin, Ceramic, Metal

Material used to create a solid fixture for testing purposes



Contact probes

Devices used to establish an electrical connection with the object being tested.



Contact probes

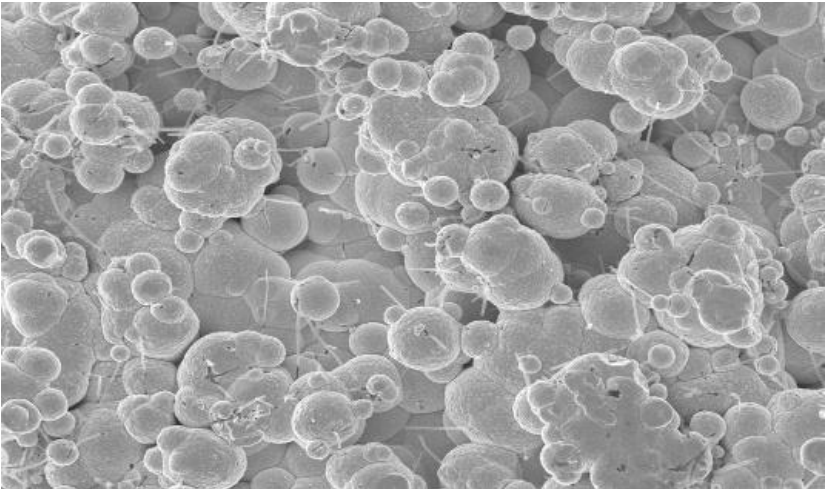
- At the core of our product line are contact probes, which serve as terminals that make direct contact with the test object.
- Our contact probes are embedded in resin or ceramic, creating specialized objects known such as probe cards, sockets and other jigs.



High-current Probes

CNT plating for contact probes. 📏

Gold-plated probes are standard—but integrating CNT enables stable handling of higher currents.



TestConX 2025 (winning a poster award)



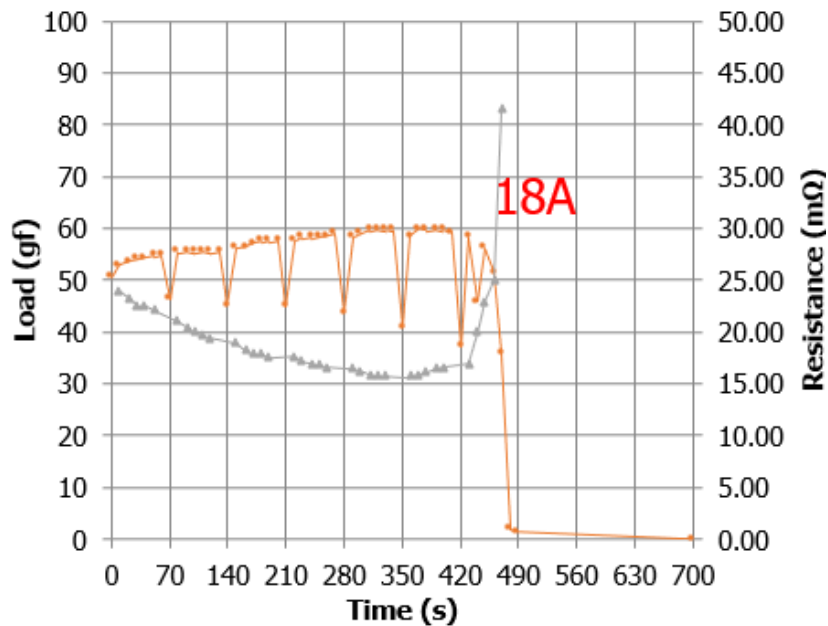
- High current capacity.
- Minimized resistance.
- Heat dissipation.
- Improved AC performance.
- Hassle-free maintenance.

Designed for high currents!

High-current Probes

CNT plating for contact probes.

Probes load and resistance



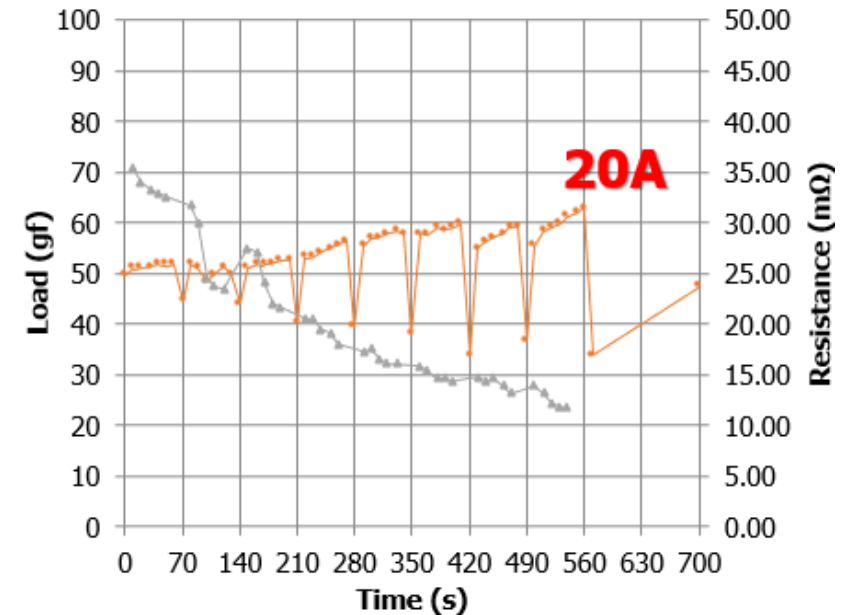
Conventional probes:

- Current: 18A (around 9A per probe)
- Observation: load decrease.
- Up to 8A per probe.

AuCNT probes:

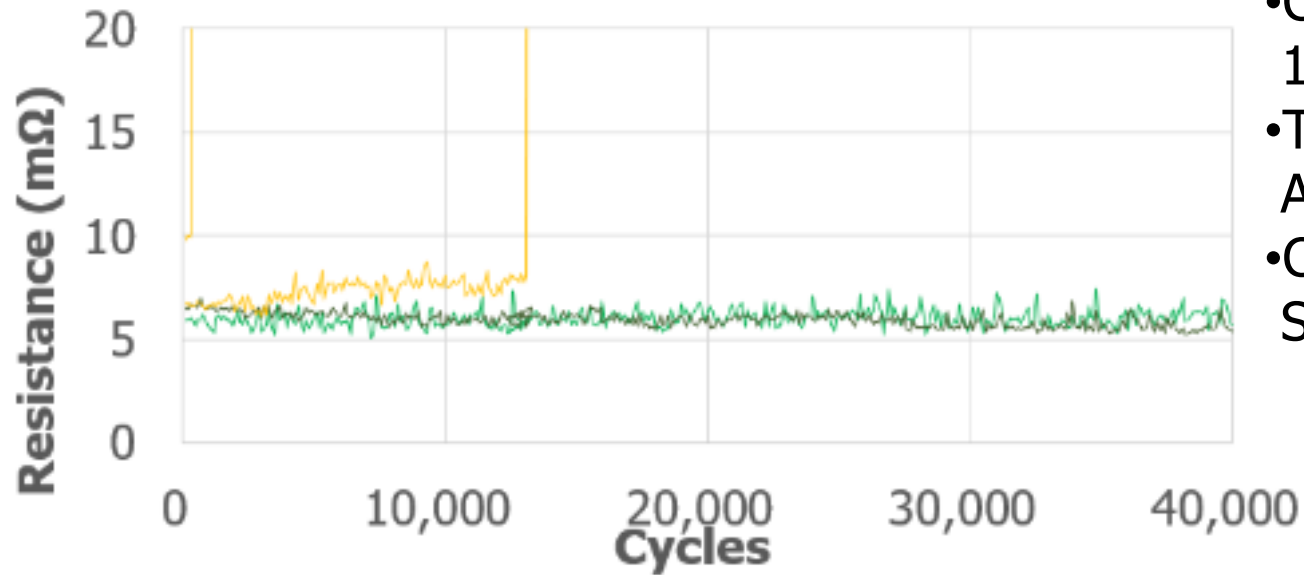
- Current: 20A (10A per probe)
- Observation: load decrease, 5%.
- Up to 10A per probe.

Probes load and resistance



High-current Probes

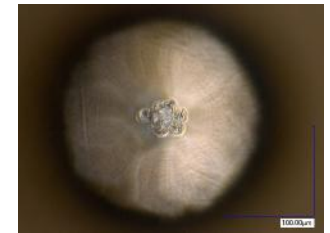
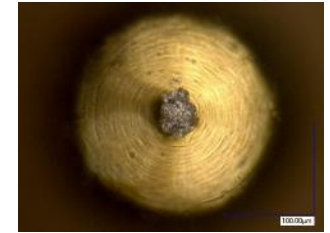
CNT plating for contact probes.



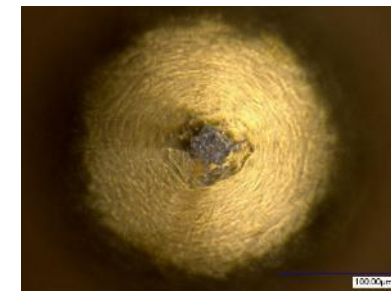
Testing conditions:

- Current:
120A for 1ms
- Target Material:
Au film on Cu block
- Contact probes:
SL-1 (2mm pitch)

After testing



After Cleaning



After testing

High-current Socket

High-Current Cube (HC-C)

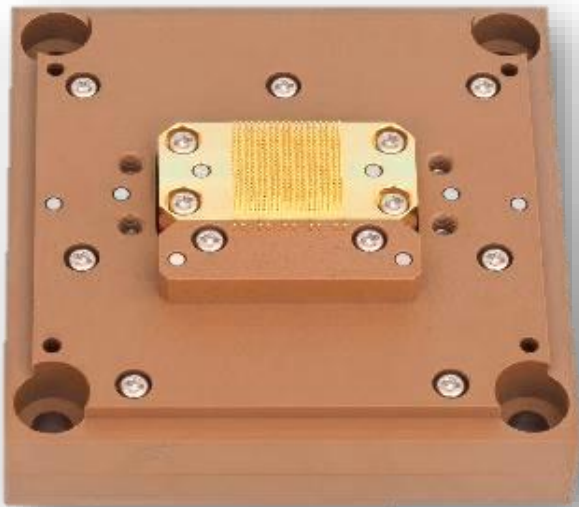
- **Exceptional current capacity** in a compact ~10mm block; up to 400A per block.
- **Improved heat dissipation** and terminal degradation under heavy loads.
- **Flexible & customizable.** Supports individual signal extraction (emitter-gate) for power devices.

Compact modular blocks for ultra-high current IC testing



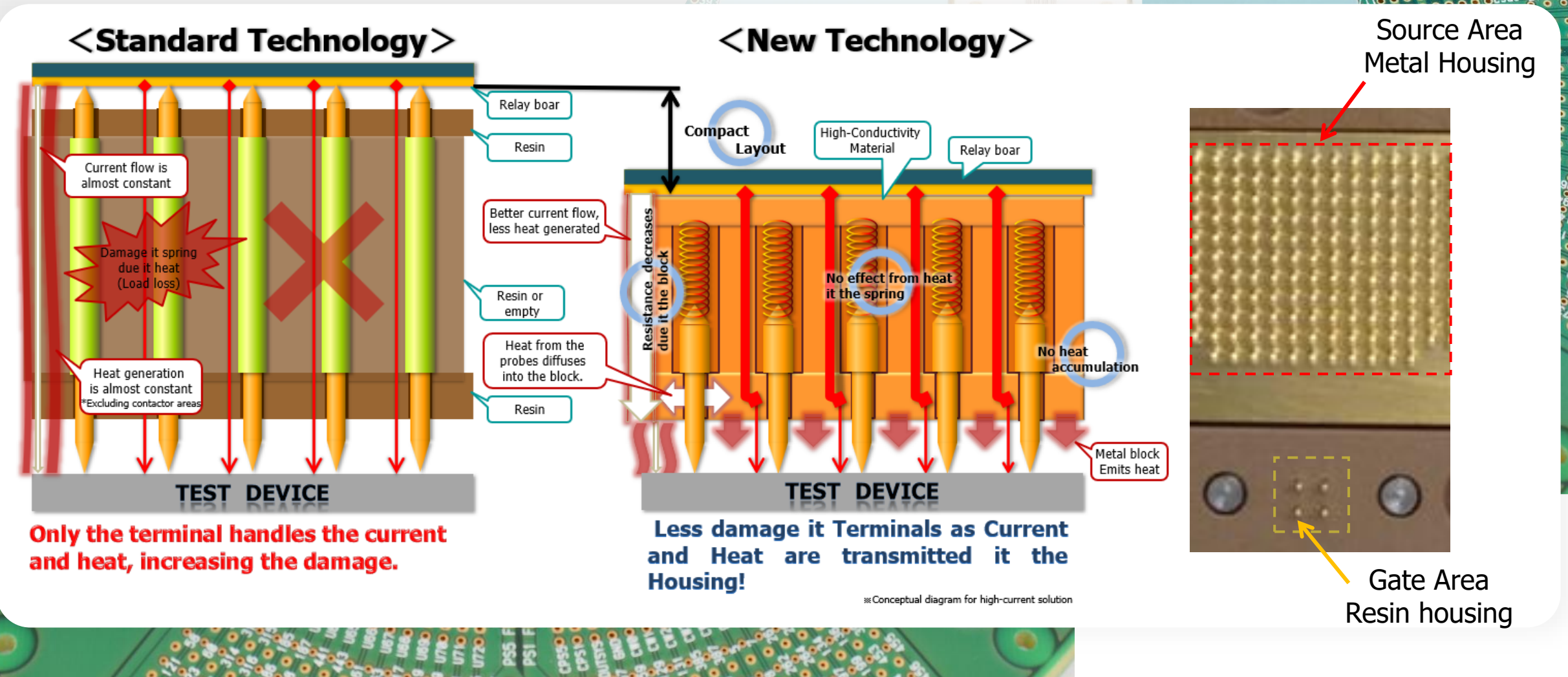
High-current probe cards

They enable “several hundred amps” of current through device electrodes. All probe cards are fully customizable to match any wafer tester or handler.

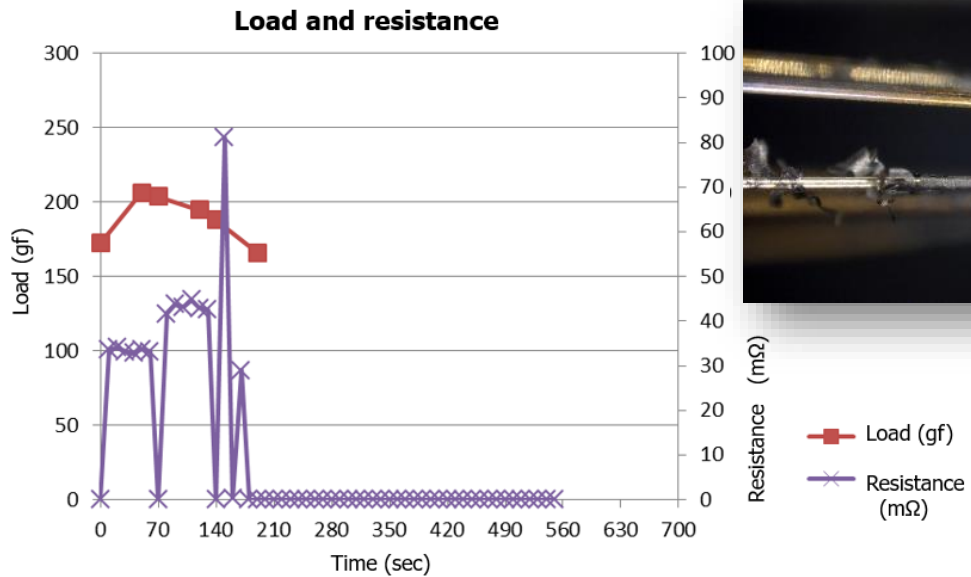


- Increased **current handling capacity** per pin and reduced resistance.
- Increased **dissipation of heat** into metal housing.
- Enhanced AC characteristics.**
- Easy maintenance**, allowing you to perform probe replacements.

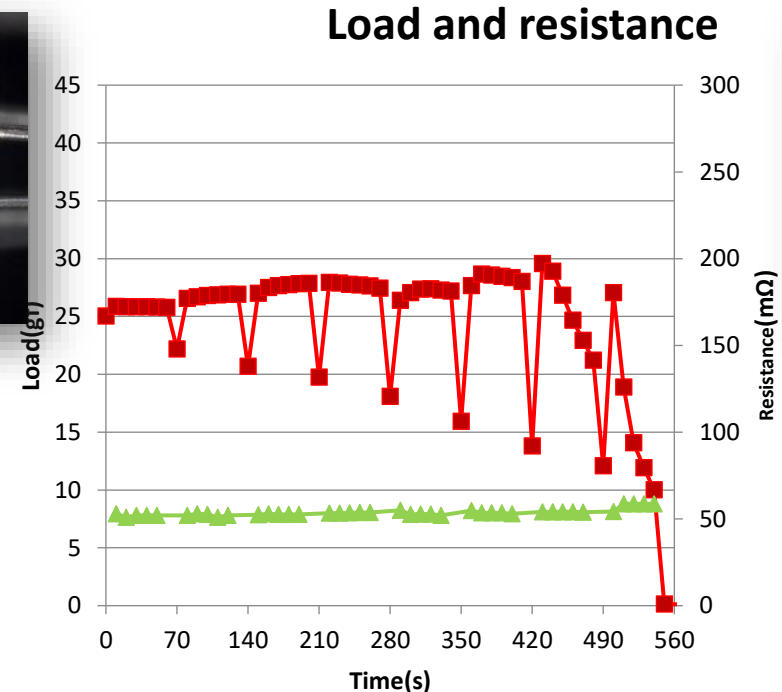
High-current probe cards



High-current probe cards



When 1A per probe was reached, the coating burned, causing sliding performance.



Test up to 6A without resistance or load-related issues.

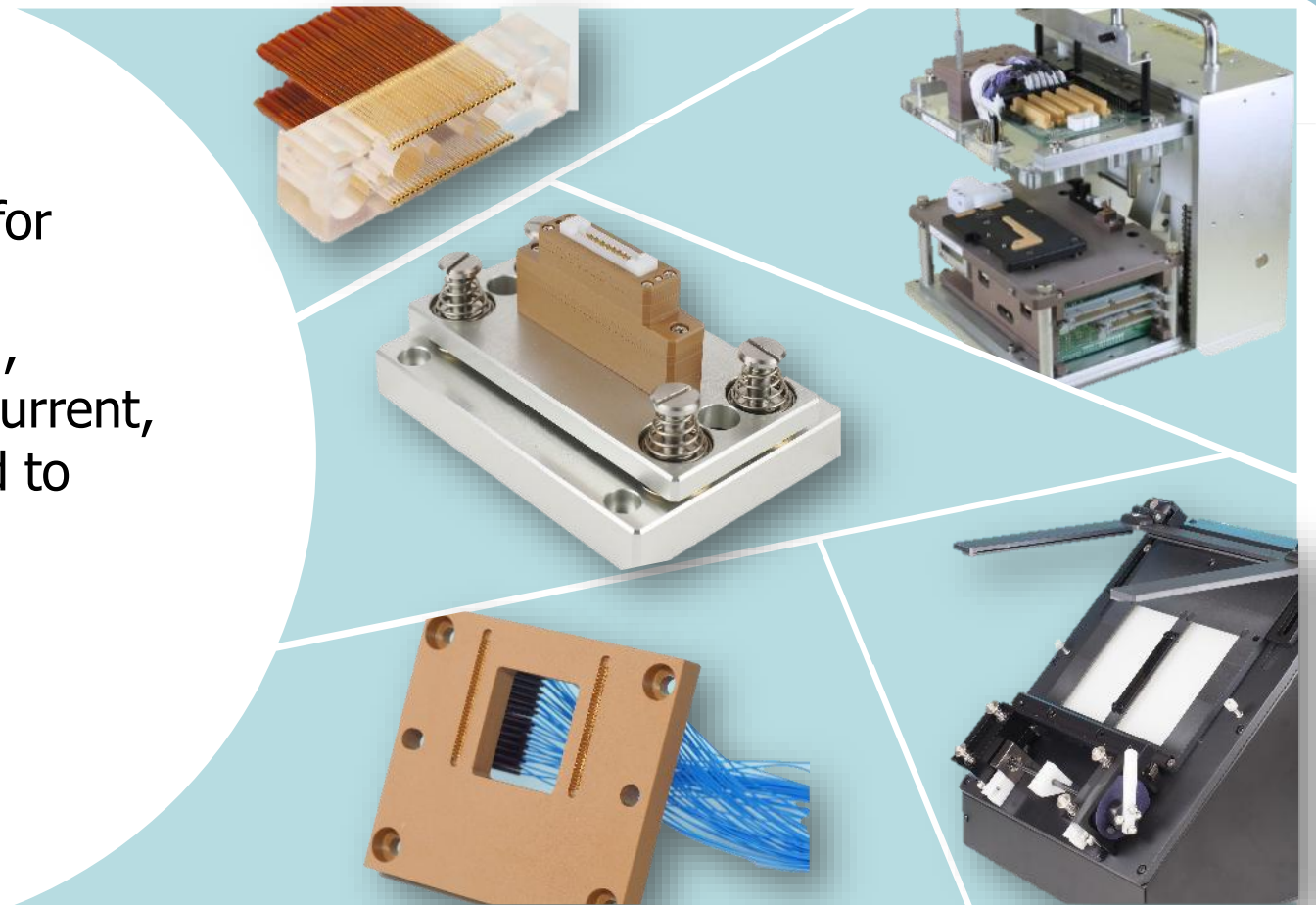
Parameters:
Start at 1A
60 seconds on
10 seconds off
Increase in 1A

High-current fixtures

Stable & reliable contact — prevents misalignment and secures measurements for consistent results.

Fully custom designs — materials (resin, metal), pitch, environmental specs (High-current, non-magnetic, high-temp, etc.) engineered to your needs.

Scalable workflow — from single-unit prototypes to mass-production fixtures — integrated wiring & connectors available.



Built for Accuracy. Designed for Your Device.

Test application

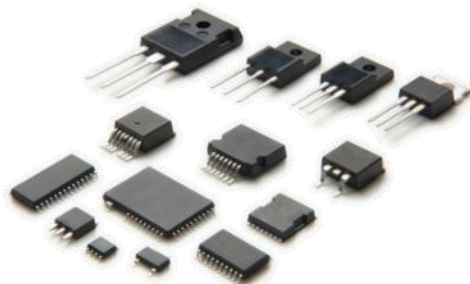
Power device
(IGBT/SiC/GaN)
testing

EV inverter chip/wafer
evaluation



High-voltage
module testing

Automotive/inverter
power modules (HV
MOSFETs, diodes)



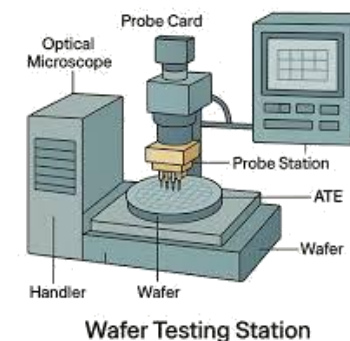
Battery & solar
power testing

Pouch-cell
charge/discharge;



Multi-die probe
cards

Parallel chip testing on
wafer.
(power BGA/LGA)





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for next-generation semiconductor testing.

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